

3A Avg.

20 Volts

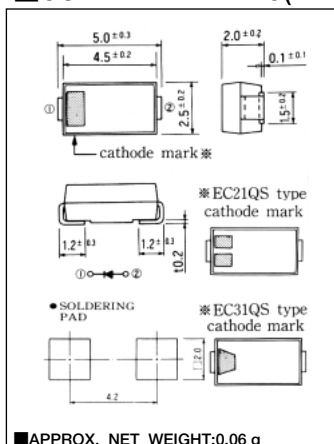
SBD

EC30LA02

■最大定格 Maximum Ratings

Item	Symbol	Conditions			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	20			V
非くり返しピーク逆電圧*1 Non-repetitive Peak Reverse Voltage	V_{RSM}	25			V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	Ta=25℃*2	2.1	A
			Tl=85℃ Tl:lead Temperature	3.0	A
実効順電流 R.M.S. Forward Current	$I_F(RMS)$	471			A
サージ順電流 Surge Forward Current	I_{FSM}	50	50Hz正弦半波, 1 サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive		A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+125			℃
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+125			℃

■ OUTLINE DRAWING(mm)



■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions		Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I _{RM}	T _j =25℃, V _{RM} =V _{RRM}		—	—	3	mA
ピーク順電圧 Peak Forward Voltage	V _{FM}	T _j =25℃, I _{FM} =3.0A		—	—	0.39	V
熱抵抗 Thermal Resistance	R _{th(j-a)}	接合部・周囲間 Junction to Ambient	Alumina Substrate Mounted*2	—	—	108	℃/W
	R _{th(j-l)}	接合部・リード間 Junction to Lead	—	—	—	23	℃/W

*1: パルス幅1 μ s以下、Duty 1/50以下 Pulse Width $\leq 1 \mu$ s, Duty $\leq 1/50$

*2: アルミナ基板実装/Alumina Substrate mounted (Soldering Lands=2×2mm, Both Sides)

※ 平均順電流定格図は、逆電力損失を含まない値です。実使用に際しましては、逆電力損失による熱暴走にご注意ください。

■定格・特性曲線

FIG.1

順電壓特性
FORWARD CURRENT VS. VOLTAGE

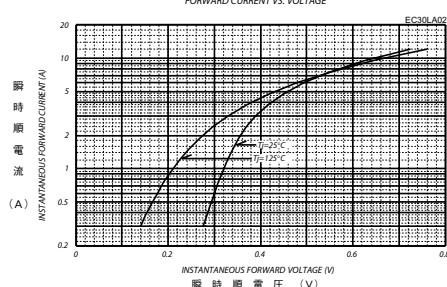


FIG.2

平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

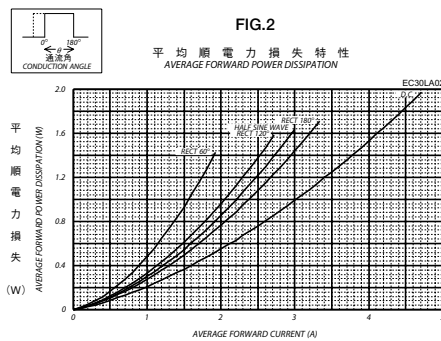


FIG.3

ピーク逆電流 — ピーク逆電圧特性
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE

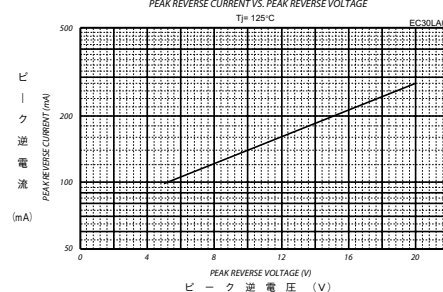


FIG.4

平均逆電力損失
AVERAGE REVERSE POWER DISSIPATION

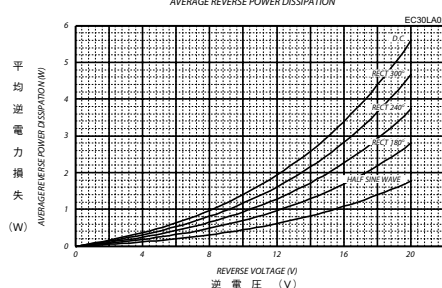


FIG.5

平均順電流一周圍溫度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

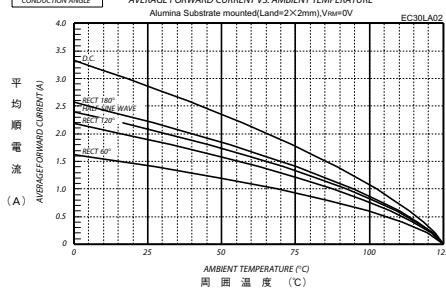


FIG.6

平均順電流—リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

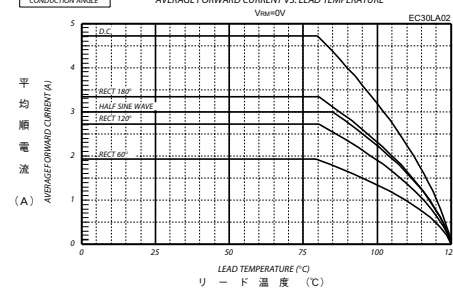


FIG.7

サージ順電流定格
SURGE CURRENT RATINGS
f=50Hz Half Sine Wave, Non-Repetitive, No Load

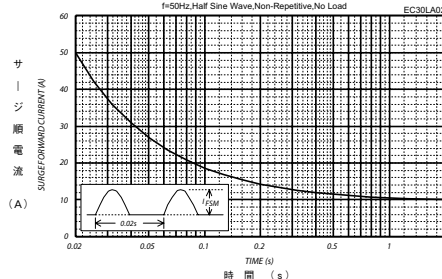


FIG.8

接合容量特性
JUNCTION CAPACITANCE VS. REVERSE VOLTAGE
T_a:25°C V_{ana}:20mV/sec. f_i:100kHz Typical Value

